

**AMENDMENTS TO THE CLAIMS**

Please cancel claims 3 and 16, and amend claims 1, 4-6, 10, 13 and 14. No new matter is believed to be introduced by the aforementioned amendments and new claims. The following listing of claims will replace all prior versions and listings of claims in the application.

1. **(Currently Amended)** An optoelectronic arrangement, comprising:
  - at least one emission component,
  - a monitor component, ~~which~~ is operatively coupled to the emission component and ~~detects at least some~~ ~~detecting~~ radiation radiated by the emission component,
  - a driver circuit electrically connected to the emission component and the monitor component, and
  - a carrier substrate,
  - the driver circuit being formed as a circuit integrated into the carrier substrate,
  - the monitor component likewise being integrated into the carrier substrate, and
  - the emission component being formed as a separate structural part and ~~being arranged on the carrier substrate comprising a vertically emitting laser component which is fixed above the monitor component on the carrier substrate, part of the laser light being radiated upward and part of the laser light being radiated downward on to the monitor component, the laser component comprising a laser resonator and a laser substrate in which:~~
    - ~~the laser resonator is arranged at a side of the laser component which is remote from the carrier substrate, and the laser substrate has, at a side facing the carrier substrate and in a manner adjoining the laser resonator, a cutout in such a way that downwardly radiated light falls on to the monitor component; or~~
    - ~~the laser resonator is arranged at a side of the laser component which faces the carrier substrate, and the laser substrate has, at a side remote from the carrier substrate and in a manner adjoining the laser resonator, a cutout that facilitates radiating light away from the carrier substrate.~~
2. **(Previously Presented)** The arrangement according to Claim 1, the monitor component comprising a photodiode having a pn junction integrated into the carrier substrate.
3. **(Cancelled)**

4. **(Currently Amended)** The arrangement according to Claim [[3]] 1,  
the laser component comprising a laser substrate and a laser resonator,  
the laser resonator being arranged at a side of the laser component which is remote from  
the carrier substrate, and  
the laser substrate having, at a side facing the carrier substrate and in a manner adjoining  
the laser resonator, a cutout in such a way that downwardly radiated light falls on to the monitor  
component.
5. **(Currently Amended)** The arrangement according to Claim [[3]] 1,  
the laser component comprising a laser substrate and a laser resonator,  
the laser resonator being arranged at a side of the laser component which faces the carrier  
substrate, and  
the laser substrate having, at a side remote from the carrier substrate and in a manner  
adjoining the laser resonator, a cutout that facilitates radiating light away from the carrier  
substrate.
6. **(Currently Amended)** The arrangement according to Claim 5, the laser component  
being arranged with a top side facing toward the carrier substrate and in this case having one or more  
electrical contacts located at the top side.
7. **(Previously Presented)** The arrangement according to Claim 1, the emission component  
being formed as a laser chip.
8. **(Previously Presented)** The arrangement according to Claim 1, the emission component  
being connected to the carrier substrate by at least one of adhesive bonding and wire bonding.
9. **(Previously Presented)** The arrangement according to Claim 1, the emission component  
being connected to the carrier substrate by flip-chip mounting.
10. **(Currently Amended)** The arrangement according to Claim [[3]] 1, further comprising  
an array of vertically emitting laser components and respectively assigned monitor components, wherein  
at least some of the laser light is radiated downward onto the associated monitor components.

11. **(Previously Presented)** The arrangement according to Claim 10,  
the array of vertically emitting laser components having a common laser substrate and  
respective laser resonators for the laser components,  
the respective laser resonators being arranged at respective sides of the laser components  
that face the carrier substrate, and  
respective laser substrates for the laser components having, at a side remote from the  
carrier substrate and in a manner adjoining the laser resonators, respective cutouts that facilitate  
radiating light away from the carrier substrate.
12. **(Previously Presented)** The arrangement according to Claim 10, the laser components  
of the array being connected as redundant components.
13. **(Currently Amended)** The arrangement according to Claim [[3]] 1, the carrier substrate  
being transparent to the radiated light.
14. **(Currently Amended)** The arrangement according to Claim [[3]] 1, the emission  
component emitting light having a wavelength of between 650 and 850 nm.
15. **(Previously Presented)** The arrangement according to Claim 14, wherein the emission  
component comprises GaAs.
16. **(Canceled)**
17. **(Previously Presented)** The arrangement according to Claim 1, wherein the driver  
circuit is integrated monolithically into the carrier substrate.
18. **(Previously Presented)** The arrangement according to Claim 1, wherein the monitor  
component is integrated monolithically into the carrier substrate.
19. **(Previously Presented)** The arrangement according to Claim 1, wherein the monitor  
component comprises a diode.

20. **(Previously Presented)** The arrangement according to Claim 19, wherein the emission component comprises a laser chip, the diode being integrated monolithically into the carrier substrate and the laser chip being located on the carrier substrate above the diode.